



Future Normal in Semiconductor

2025-02-14(금), 10:55-12:40

좌장: 추후업데이트 예정

A. Interconnect & Package 분과

[FD2-A] Advanced Package 1

FD2-A-1 10:55-11:10	Study on Novel Corrosion Inhibitors in Molybdenum CMP Hyeonjeong Lee, Pengzhan Liu, and Taesung Kim Department of Mechanical Engineering, Sungkyunkwan University
FD2-A-2 11:10-11:25	Plasma Treatment and Electrical Characterization for Enhanced RDL Adhesion on PSPI in Advanced Packaging Sunbum Kim ¹ , Gyulee Kim ¹ , Kyoungyeon Min ² , Dugkyu Han ¹ , and Changhwan Choi ^{1,2} ¹ Division of Materials Science and Engineering, Hanyang University, ² Department of Semiconductor Engineering, Hanyang University
FD2-A-3 11:25-11:40	Ultrastable 3D Heterogeneous Integration via N-Heterocyclic Carbene Self-Assembled Nanolayers Jinhyoung Lee and Taesung Kim Sungkyunkwan University
FD2-A-4 11:40-11:55	3D-Printed Organic Substrates for Low-Cost, Re-Distribution-Layer-Less Fanout Interposers Haksoon Jung ¹ , Nahyeon Kim ¹ , and Jimin Kwon ^{1,2} ¹ Department of Electrical Engineering, UNIST, ² Graduate School of Semiconductor Materials and Devices Engineering, UNIST
FD2-A-5 11:55-12:10	Enhancing HBM3E KGSD Quality Competitiveness through the Implementation of Gray AI-Based Technology Sung Hyun Yoon and Sang Yup Lee ¹ SK hynix, ² Yonsei University
초청 FD2-A-6 12:10-12:40	Bonding mechanism at the Cu-Cu interface in hybrid bonding: Crystal plasticity theory and experimental validation Eun-Ho Lee ^{1,2} ¹ School of mechanical Engineering, Sungkyunkwan University, ² Department of Smart Fab. technology, Sungkyunkwan University